

■ Features

- Minature size,suitable for SMT.
- Using terminal electrode structure to restrain the parasitic component effect quite caused by lead.
- Excellent in solderability and heat resistance.
- Best frequency special property and intense ability to resist interference.
- Operating temperature:-40℃ ~ +85℃.

■ Applications

- Protable communication equipment and PDA,high speed electronic device.
- Used for radiation high speed noise suppression.

■ Product Identification

$\frac{\text{YWIF}}{(1)}$
 $\frac{\square\square\square\square}{(2)}$
 $-\frac{\square\square\square}{(3)}$
 $-\frac{\square}{(4)}$

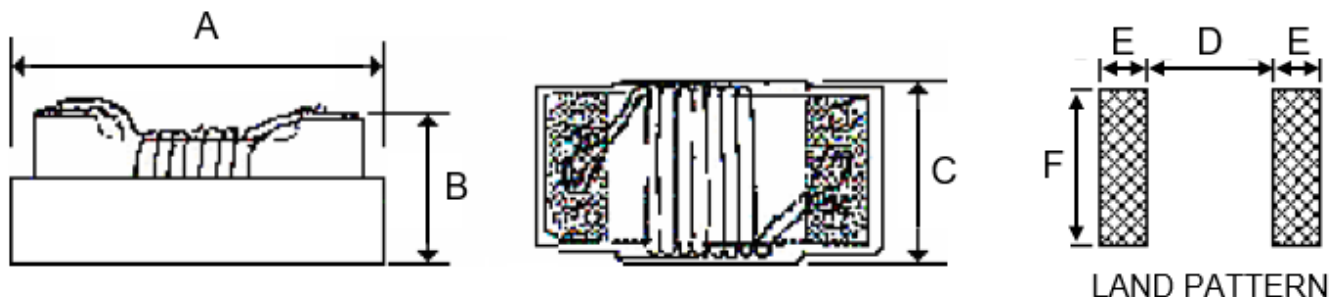
(1) : Type

(2) : Dimensions

(3) : Inductance value

(4) : Inductance Tolerance: M=±20%,K=±10%,J=±5%

■ Shapes and Dimensions (Unit: mm)



TYPE	A Max.	B Max.	C Max.	D Typ.	E Typ.	F Typ.
YWIF1005	1.19	0.64	0.70	0.46	0.36	0.66

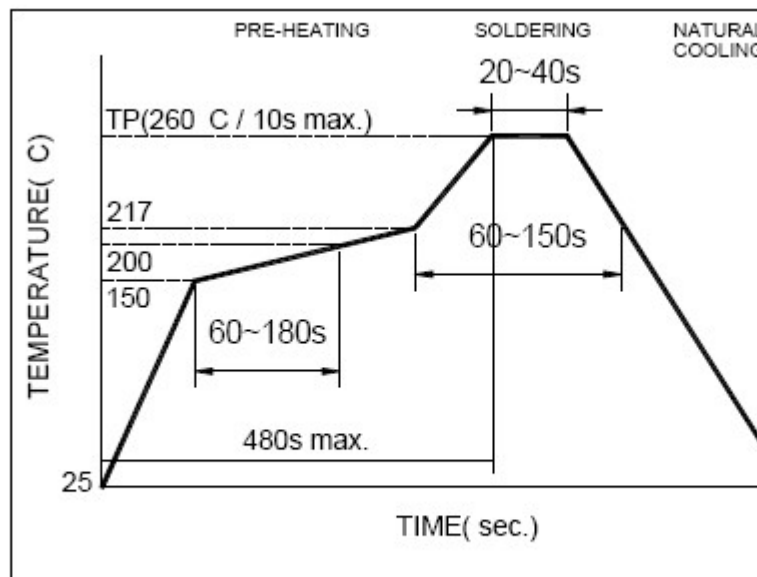
■ YWIF1005 Series

Part Number	L (nH)	Freq. (MHz)	SRF Min. (MHz)	Rdc Max. (Ω)	Isat Max. (mA)
YWIF1005-78NK	78 $\pm$ 10%	7.9	1600	0.13	970
YWIF1005-R10K	100 $\pm$ 10%	7.9	1400	0.16	900
YWIF1005-R11K	110 $\pm$ 10%	7.9	1000	0.20	850
YWIF1005-R12K	120 $\pm$ 10%	7.9	1000	0.20	850
YWIF1005-R14K	140 $\pm$ 10%	7.9	1220	0.26	630
YWIF1005-R15K	150 $\pm$ 10%	7.9	1220	0.26	630
YWIF1005-R18K	180 $\pm$ 10%	7.9	1150	0.28	560
YWIF1005-R20K	200 $\pm$ 10%	7.9	1000	0.44	400
YWIF1005-R22K	220 $\pm$ 10%	7.9	1150	0.53	380
YWIF1005-R25K	250 $\pm$ 10%	7.9	900	0.90	360
YWIF1005-R27K	270 $\pm$ 10%	7.9	860	0.90	360
YWIF1005-R30K	300 $\pm$ 10%	7.9	860	0.90	360
YWIF1005-R36K	360 $\pm$ 10%	7.9	810	0.90	250
YWIF1005-R39K	390 $\pm$ 10%	7.9	760	1.00	200
YWIF1005-R47K	470 $\pm$ 10%	7.9	650	1.00	200
YWIF1005-R56K	560 $\pm$ 10%	7.9	600	1.20	200
YWIF1005-R82K	820 $\pm$ 10%	7.9	385	5.85	90
YWIF1005-1R0K	1000 $\pm$ 10%	7.9	200	6.50	50

- ※ Saturation DC current: Inductance drop approximately 30% of L0 at Isat.
- ※ Storage temp.: -10 $^{\circ}$ C ~ + 40 $^{\circ}$ C R.H.: 65% Max.
- ※ Moisture sensitivity level (MSL) 2 (1 year floor life at <30 $^{\circ}$ C / 65% relative humidity)

■ Soldering Conditions

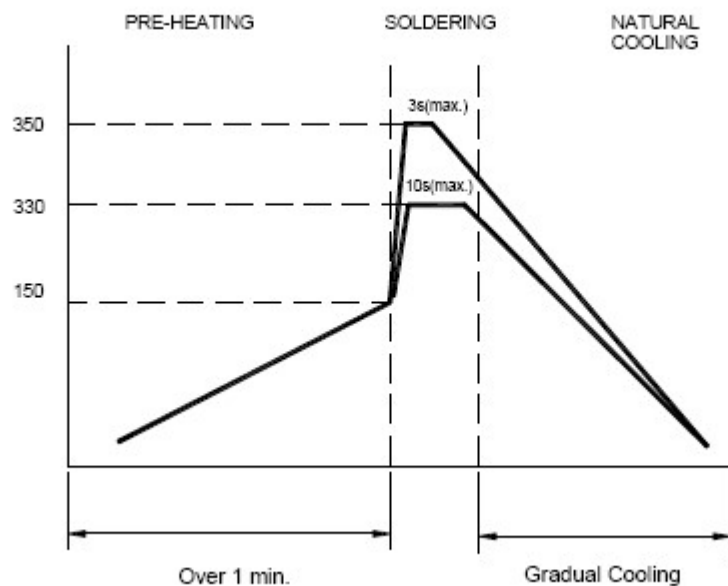
Figure 1.
Re-flow
Soldering
(Lead Free)



Note:

- Preheat circuit and products to 150°C
- 260°C tip temperature (max)
- Reflow times: no more than 2 times
- Solder paste thickness: the best 0.08mm is, but max is 0.1mm

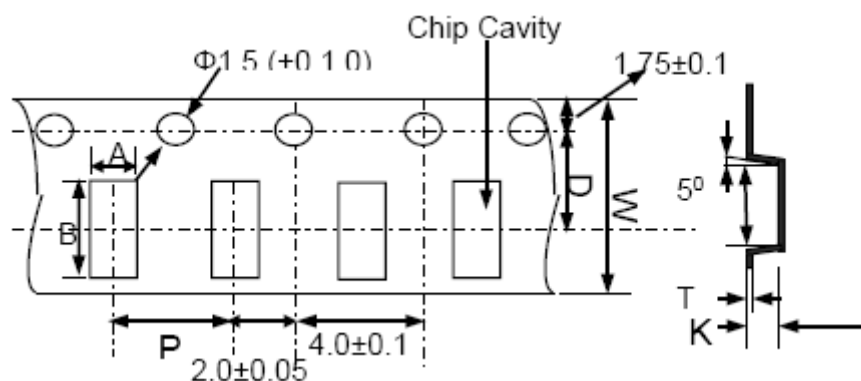
Figure 2.
Hand
Soldering



Note:

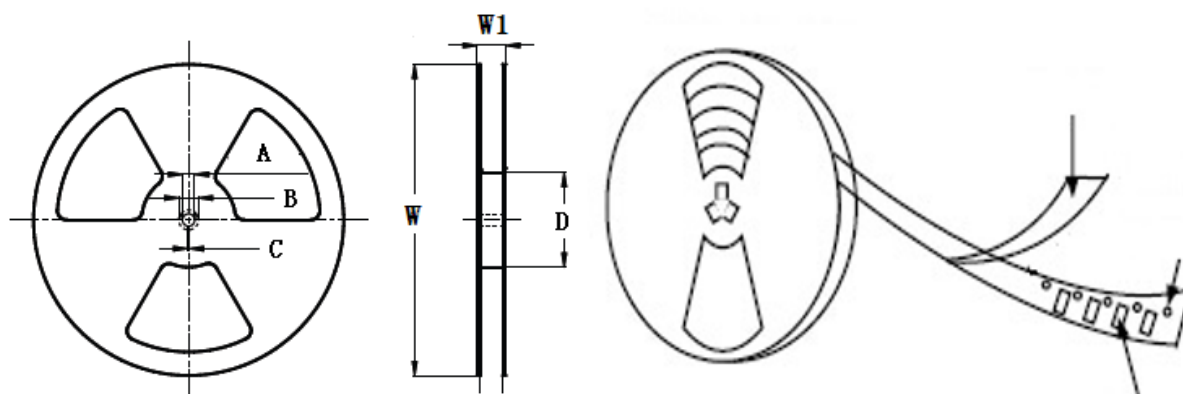
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- Limit soldering time to 3 sec.

■ Taping Dimensions(Unit:mm)



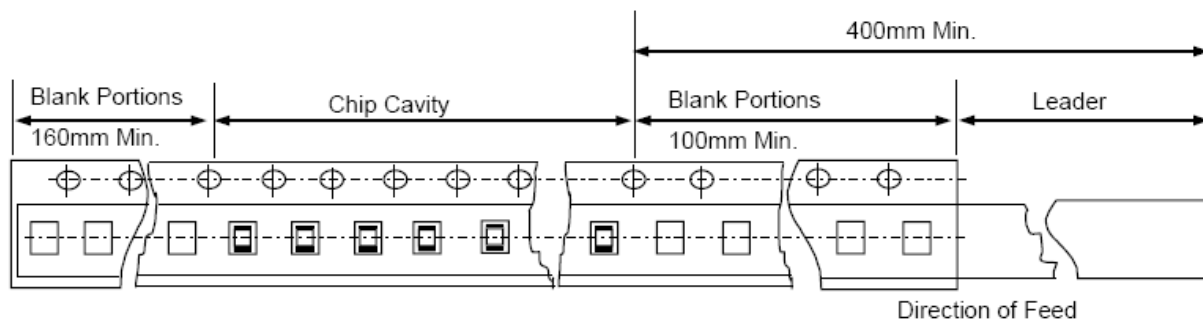
TYPE	W	A	B	D	P	K Max	T Max	MPQ
YWIF1005	8.00	1.50	2.30	3.50	4.00	1.10	0.30	10000

■ Reel Dimensions(Unit:mm)



TYPE	W	W1	A	B	C	D
YWIF1005	178±2.0	8.40±1.50	4.3±0.20	5.0±0.10	3.0±0.10	58±2.0

■ Leader and Blank portion



1. Missing chips number within 0.1% of the number per reel or 1pcs, whichever is greater, and are not continuous.
2. The top tape and bottom tape shall not protrude beyond the edges of the tape and shall not cover sprocket hole.
3. Cumulative tolerance of sprocket holes, 10 pitches: $\pm 0.3\text{mm}$.
4. Peeling off force: 10gf to 100gf in the direction show below for 8mm carrier tapes and 10gf to 130gf for 12mm to 56mm wide carrier tapes.

